

Title (en)
THICK-WIRE BOND ARRANGEMENT AND METHOD FOR PRODUCING

Title (de)
DICKDRAHT-BONDANORDNUNG UND VERFAHREN ZUM HERSTELLEN

Title (fr)
SYSTÈME DE CÂBLAGE À FIL ÉPAIS ET PROCÉDÉ DE FABRICATION

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Application
EP 11810567 A 20110907

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Abstract (en)
[origin: WO2012062300A2] The invention relates to a thick-wire bond arrangement, having a substrate (2), a thick wire (1) and a high-voltage thick-wire bond connection, where an end bond section (4) of the thick wire (1), which extends towards the end (7) of the thick wire (1), is bonded to the substrate (2), such that a bond contact (5) between the thick wire (1) and the substrate (2) is formed in the region of the bond section (4), the thick wire (1) having a tapering section (6) which adjoins the end (7) of the wire and in which the cross-section of the wire tapers towards the end (7) of the wire. The application further relates to a method for producing a thick-wire bond arrangement.

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